L Number	Hits	Search Text	DB	Time stamp
1	227	257/687		2004/07/08 20:49
			EPO; JPO; DERWENT; IBM TDB	
2	1177	257/687		2004/07/08 20:58
3	1684	257/704	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/07/08 21:08
4	1397	257/762	EPO; JPO; DERWENT; IBM_TDB	2004/07/08 21:35
	133.		US-PGPUB; EPO; JPO; DERWENT; IBM TDB	
5	1854	257/763	US-PGPUB; EPO; JPO; DERWENT;	2004/07/08 21:52
6	812	257/766	US-PGPUB; EPO; JPO; DERWENT;	2004/07/08 21:53
_	317	257/738	IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 20:49
_	2488	257/738 and (ball or bump or BGA or array)		2004/07/08 12:24
-	2208	257/738 and (ball or bump or BGA or array or flip)	USPĀT	2004/07/08 12:24
_	2510	257/738 and (ball or bump or BGA or array or flip)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/08 12:25
_	2488	257/738 and (ball or bump or BGA or array)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 12:25
- -	2188 1954	257/738 and (ball or bump or BGA or array) 257/738 and (ball or bump or BGA or array) and wir\$3	USPAT USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/08 12:25 2004/07/08 13:46
-	1954	257/738 and (ball or bump or BGA or array) and wir\$3	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/08 13:58
-	2670	257/738	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/08 13:51
_	716	257/738 not (257/738 and (ball or bump or BGA or array) and wir\$3)	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 13:51

-	5257	257/666	USPAT;	2004/07/08 13:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1672	057/666	IBM_TDB	0004/07/00 14:07
_	1673	257/666 and (ball or bump or BGA or array)	USPAT; US-PGPUB;	2004/07/08 14:27
		and wir\$3	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	323	257/667 and (ball or bump or BGA or array)	USPAT;	2004/07/08 14:27
	1 323	and wir\$3	US-PGPUB;	2001,0,,00 11.2.
		W1240	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	3167	257/666	USPĀT	2004/07/08 15:34
-	1671	257/666 not (257/666 and (ball or bump or	USPAT	2004/07/08 14:29
İ		BGA or array) and wir\$3)		
-	0	conductive near epoxy with 257/777	USPAT	2004/07/08 14:31
-	34	electrically near conductive near epoxy	USPAT	2004/07/08 14:35
		and 257/777	IICDAM.	2004/07/00 14:24
-	39	electrically near conductive near epoxy	USPAT	2004/07/08 14:34
	100	and (438/108 or 438/109)	USPAT	2004/07/08 14:35
	188	conductive near epoxy and 257/777 electrically with conductive near epoxy	USPAT	2004/07/08 14:35
-	"	and 257/777	001111	2001/07/00 14:50
_	98	electrically with conductive near epoxy	USPAT	2004/07/08 14:40
		and (257/777 or 438/108 or 438/109)		
_	134	electrically with conductive near epoxy	USPAT	2004/07/08 14:50
		and (257/777 or 438/108 or 438/109 or		
		257/686)		
-	141	electrically with (conductive or "Ag" or	USPAT	2004/07/08 14:56
		silver) near epoxy and (257/777 or 438/108		
		or 438/109 or 257/686)		
-	0	electrically with (conductive or "Ag" or	JPO	2004/07/08 14:54
		silver) near epoxy and (257/777 or 438/108		
	170	or 438/109 or 257/686) electrically with (conductive or "Ag" or	USPAT	2004/07/08 15:21
-	172	silver) near epoxy and (257/777 or 438/108	USFAI	2004/07/00 13:21
		or 438/109 or 257/686 or 361/760)		
_	320	electrically with (conductive or "Ag" or	USPAT	2004/07/08 15:22
		silver) with epoxy and (257/777 or 438/108		
		or 438/109 or 257/686 or 361/760)		
-	235	electrically with (conductive or "Ag" or	USPAT	2004/07/08 15:22
		silver) with epoxy and (257/777 or 438/108		
		or 438/109 or 257/686 or 361/760) and		
1	505	(ball or bump)	HCDAM	2004/07/08 15:34
-	685	257/667 257/667	USPAT;	2004/07/08 15:34
-	945	231/001	US-PGPUB;	2004/01/00 10.03
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
-	778	257/673	USPAT;	2004/07/08 16:15
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	0004/07/00 15 15
-	3181	257/676	USPAT;	2004/07/08 16:10
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
1_	2245	257/676	USPAT	2004/07/08 16:11
_	3329	257/773	USPAT;	2004/07/08 16:15
1			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
1	1		IBM_TDB	
-	2717	257/773	USPAT	2004/07/08 16:39
-	2719	257/774	USPAT	2004/07/08 16:55
-	972	257/776	USPAT	2004/07/08 16:55

	1162	257/776	USPAT;	2004/07/08 17:10
	1102	231/110	US-PGPUB;	2004,07,00 17.10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	2518	257/784	USPAT;	2004/07/08 17:10
-	2510	2377704	US-PGPUB;	2004,07,00 17.10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	1783	257/784	USPAT	2004/07/08 17:19
_	861	257/684	USPAT	2004/07/08 17:20
_	1062	257/684	USPAT;	2004/07/08 17:45
	1002	2377 004	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2342	257/698	USPĀT;	2004/07/08 17:49
1	2312	20.7 030	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3932	257/778	USPĀT;	2004/07/08 17:49
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3410	257/778	USPAT	2004/07/08 18:11
-	2231	257/678	USPAT	2004/07/08 18:57
_	902	257/781	USPAT	2004/07/08 18:57
-	1001	257/781	USPAT;	2004/07/08 18:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

and the sale